

DESCRIPTION

Lingsen MEMS Pressure is a wire bonded and cap seal on substrate system in package. It will possess light, thin, short and small advantage. MEMS (Micro Electro-Mechanical system) Pressure can be used in communication and consumption products etc..

APPLICATIONS

- Hard Disc/ GPS/ Cell phone

FEATURES

- Automatic assembly
- Full in-house design and test capability

RELIABILITY

- Pre-condition: Temperature cycle from - 65°C ~ + 150°C (5 cycles)/ Bake 125°C/ 24 hrs/Soak 85°C / 85 % R.H.(168 hrs)/IR-Reflow , 3 cycles (lead free 260)TCT : -40°C ~125°C(1000 cycles)HTOL: 125C, 1000hrs, 0.55mA
THT: 85 C, 85 %RH, 1000hrs, 0.55mA
- Drop test: 1500G
- High temp storage: 150C, 1000 hrs
- Low temp storage: -55C, 1000 hrs
- Room temp bias: 25C, 0.55mA
- HAST bias: 130C, 85%RH, 2atm, 0.55mA

- Over-pressure cycle: 10k cycles minimum (Burst Pressure 3X)
- Vibration
- Substrate bending test
- Reflow: 3 times
- ESD: 2kV

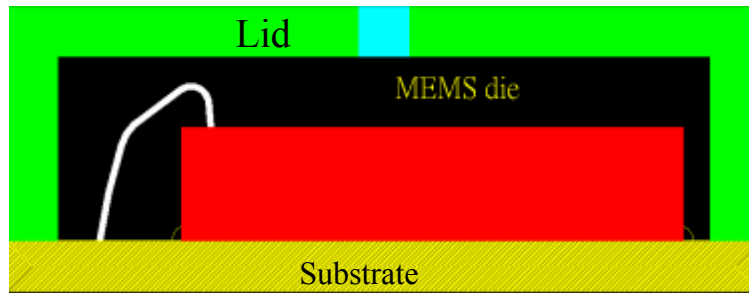
SPECIFICATIONS

- Gold Wire 99.99% Au
- Cap Plastic/ Metal
- Marking Laser Mark
- Packing Tape and Reel



Data Sheet- MEMS Pressure Sensor

CROSS-SECTION



MEMS Pressure Sensor Configuration